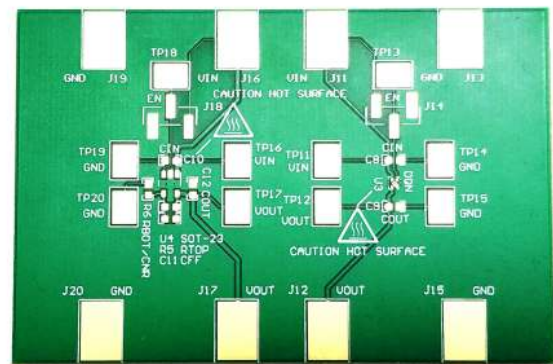
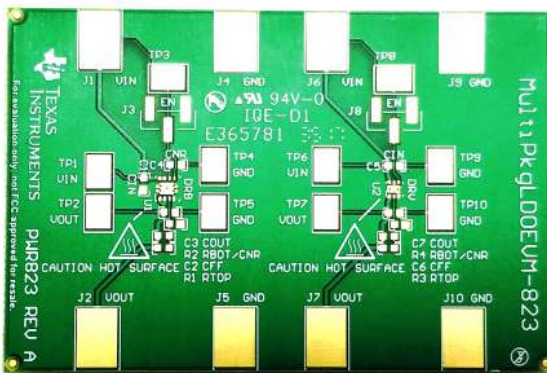


# Universal Low-Dropout (LDO) Linear Voltage Regulator MultiPkgLDOEVM-823 Evaluation Module



This user's guide describes the operational use of the MultiPkgLDOEVM-823 evaluation module (EVM) as a reference design for engineering demonstration and evaluation of Texas Instruments low-dropout (LDO) linear regulators, in DRB, DRV, DQN, and DBV packages. Included in this user's guide are setup and operating instructions, layout guidelines, a printed circuit board (PCB) layout, a schematic diagram, and a bill of materials (BOM).

Throughout this document, the terms *demonstration kit*, *evaluation board*, and *evaluation module* are synonymous with the MultiPkgLDOEVM-823.

## Contents

1	Introduction .....	3
1.1	Before You Begin .....	3
2	Supported Pinouts .....	3
3	DRB Package .....	4
3.1	Input/Output Connectors and Jumper Descriptions .....	4
3.2	Component Descriptions.....	4
3.3	EVM Setup.....	6
3.4	Operation .....	6
3.5	Schematic.....	6
4	DRV Package .....	7
4.1	Input/Output Connectors and Jumper Descriptions .....	7
4.2	Component Descriptions.....	7
4.3	EVM Setup.....	9
4.4	Operation .....	9
4.5	Schematic.....	9
5	DQN Package .....	10
5.1	Input/Output Connectors and Jumper Descriptions.....	10
5.2	Component Descriptions .....	10
5.3	EVM Setup .....	11

	5.4	Operation .....	11
	5.5	Schematic .....	11
6		DBV Package .....	12
	6.1	Input/Output Connectors and Jumper Descriptions.....	12
	6.2	Component Descriptions .....	12
	6.3	EVM Setup .....	14
	6.4	Operation .....	14
	6.5	Schematic .....	14
7		PCB Layout .....	15
8		Bill of Materials .....	16

### List of Figures

1	Supported Packages and Pinouts .....	3
2	MultiPkgLDOEVM-823 DRB Schematic .....	6
3	MultiPkgLDOEVM-823 DRV Schematic .....	9
4	MultiPkgLDOEVM-823 DQN Schematic .....	11
5	MultiPkgLDOEVM-823 DBV Schematic.....	14
6	Top Layer Assembly .....	15
7	Bottom Layer Assembly .....	15
8	Top Layer Routing .....	15
9	Bottom Layer Routing.....	15

### List of Tables

1	MultiPkgLDOEVM-823 BOM.....	16
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## Trademarks

All trademarks are the property of their respective owners.

## 1 Introduction

Texas Instruments' MultiPkgLDOEVM-823 EVM helps design engineers evaluate the operation and performance of several common packages of linear regulators for possible use in their own circuit application. This particular EVM configuration contains a DRB, DRV, DQN, and DBV footprint for engineers to solder and evaluate their part.

### 1.1 Before You Begin

The following warnings and cautions are noted for the safety of anyone using or working close to the MultiPkgLDOEVM-823. Observe all safety precautions.



**Warning** Warning Hot surface. Contact may cause burns. Do not touch.

#### CAUTION

The circuit module may be damaged by overtemperature. To avoid damage, monitor the temperature during evaluation and provide cooling, as needed, for your system environment.

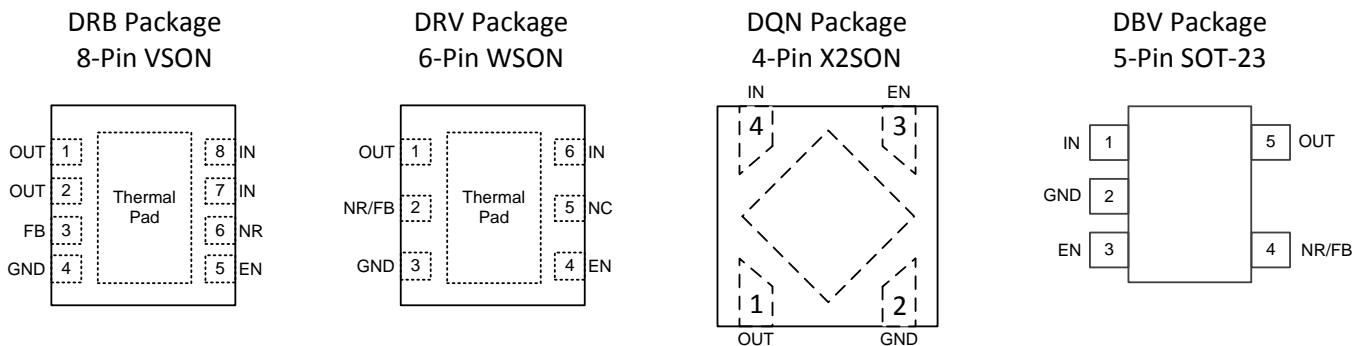
#### CAUTION

Some power supplies can be damaged by application of external voltages. If using more than one power supply, check your equipment requirements and use blocking diodes or other isolation techniques, as needed, to prevent damage to your equipment.

#### CAUTION

The circuit module is not a finished product or electrical appliance. The module does not contain current or voltage thresholds for circuit protection. It must be used by qualified personnel with additional equipment for evaluation only.

## 2 Supported Pinouts



**Figure 1. Supported Packages and Pinouts**

### 3 DRB Package

#### 3.1 *Input/Output Connectors and Jumper Descriptions*

##### 3.1.1 J1 – VIN

Input power-supply voltage connector. This is the jumper power-supply connection for the DRB package on the MultiPkgLDOEVM-823. Connect the load of the LDO to this pin.

##### 3.1.2 J2 – VOUT

Output power-supply voltage connector. This is the jumper power-supply connection for the DRB package on the MultiPkgLDOEVM-823. Connect the power supply to this jumper pin.

##### 3.1.3 J3 – EN

Output enable. To enable the output, connect a jumper to short VIN to EN.

##### 3.1.4 J4 – GND

GND jumper. Connect the GND leads of the input power supply to this jumper.

##### 3.1.5 J5 – GND

GND jumper. Connect the GND leads of the load to this jumper.

##### 3.1.6 TP1 – VIN

Input test point. Connect DMM or scope probes to this point to monitor the input voltage of the LDO.

##### 3.1.7 TP2 – VOUT

VOUT test point. Connect DMM or scope probes to this point to monitor the output of the LDO.

##### 3.1.8 TP3 – EN

This test point connects to EN. When J3 is removed, this testpoint can be used to drive the EN pin of the LDO.

##### 3.1.9 TP4 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

##### 3.1.10 TP5 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

#### 3.2 *Component Descriptions*

##### 3.2.1 C1 - Input Capacitor

Populate the recommended input capacitor for the part that is being used.

##### 3.2.2 C2 - Feedforward Capacitor

Populate the recommended feedforward capacitor for the part that is being used. Feedforward capacitors can only be used on adjustable LDOs, consult the data sheet for the proper feedforward capacitor.

**3.2.3 C3 - Output Capacitor**

Populate the recommended output capacitor for the part that is being used.

**3.2.4 C4 - Noise Reduction Capacitor**

Populate the recommended noise-reduction capacitor for the part that is being used.

**3.2.5 R1 - RTOP**

This is the top feedback resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R1. This resistor is only necessary for adjustable LDOs.

**3.2.6 R2 - RBOT**

This is the bottom feedback resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R2. This resistor is only necessary for adjustable LDOs.

### 3.3 EVM Setup

This section describes how to properly connect and setup the MultiPkgLDOEVM-823 for the DRB package, including the jumpers and connectors on the EVM board.

#### 3.3.1 Soldering Guidelines

To avoid damaging the integrated circuit (IC), use a hot-air system for any solder rework to modify the EVM for the purpose of repair or other application reasons.

#### 3.3.2 Equipment Connection

Use the following steps when connecting equipment:

1. Set the input power supplies to have a maximum voltage based on the recommended maximum in the data sheet, and turn the power supplies off.
2. Connect the positive voltage lead from the input power supply to VIN at the J1 connector of the EVM.
3. Connect the ground lead from the input power supply to GND at the J4 connector of the EVM.
4. Connect a load between OUT and GND. The connector used depends on the desired output current.
5. Disable the output by floating J3.

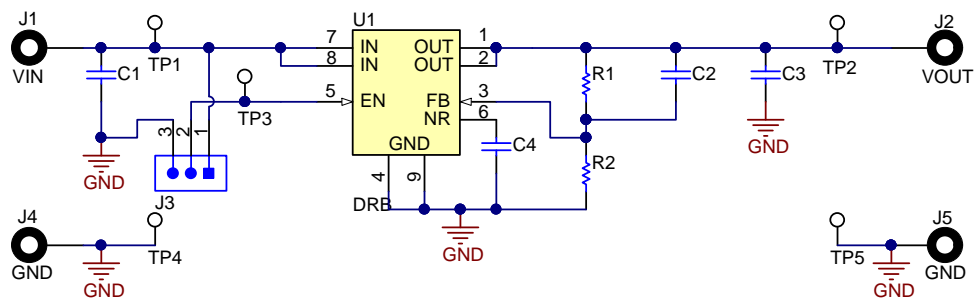
### 3.4 Operation

Operate the EVM with the following steps:

1. Turn on the power supplies.
2. Enable the output by jumping J3, the EN pin, to VIN.
3. Vary the respective load and input voltage as necessary for test purposes.

### 3.5 Schematic

Figure 2 is the schematic for the DRB portion of the EVM.



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NOTE: No components come populated on the board.

**Figure 2. MultiPkgLDOEVM-823 DRB Schematic**

## 4 DRV Package

### 4.1 Input/Output Connectors and Jumper Descriptions

#### 4.1.1 J6 – VIN

Input power-supply voltage connector. This is the jumper power-supply connection for the DRV package on the MultiPkgLDOEVM-823. Connect the load of the LDO to this pin.

#### 4.1.2 J7 – VOUT

Output power-supply voltage connector. This is the jumper power-supply connection for the DRV package on the MultiPkgLDOEVM-823. Connect the power supply to this jumper pin.

#### 4.1.3 J8 – EN

Output enable. To enable the output, connect a jumper to short VIN to EN.

#### 4.1.4 J9 – GND

GND jumper. Connect the GND leads of the input power supply to this jumper.

#### 4.1.5 J10 – GND

GND jumper. Connect the GND leads of the load to this jumper.

#### 4.1.6 TP6 – VIN

Input test point. Connect DMM or scope probes to this point to monitor the input voltage of the LDO.

#### 4.1.7 TP7 – VOUT

VOUT test point. Connect DMM or scope probes to this point to monitor the output of the LDO.

#### 4.1.8 TP8 – EN

This test point connects to EN. When J8 is removed, this testpoint can be used to drive the EN pin of the LDO.

#### 4.1.9 TP9 – GND

GND test point. Connect the GND lead of scope probes and the power supply to this point.

#### 4.1.10 TP10 – GND

GND test point. Connect the GND lead of scope probes and the power supply to this point.

### 4.2 Component Descriptions

#### 4.2.1 C5 - Input Capacitor

Populate the recommended input capacitor for the part that is being used.

#### 4.2.2 C6 - Feedforward Capacitor

Populate the recommended feedforward capacitor for the part that is being used. Feedforward capacitors can only be used on adjustable LDOs, consult the data sheet for the proper feedforward capacitor.

**4.2.3 C7 - Output Capacitor**

Populate the recommended output capacitor for the part that is being used.

**4.2.4 R3 - RTOP**

This is the top feed back resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R3. This resistor is only necessary for adjustable LDOs.

**4.2.5 R4 - RBOT**

This is the bottom feed back resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R4. This resistor is only necessary for adjustable LDOs.



### 4.3 EVM Setup

This section describes how to properly connect and setup the MultiPkgLDOEVM-823 for the DRV package, including the jumpers and connectors on the EVM board.

#### 4.3.1 Soldering Guidelines

To avoid damaging the integrated circuit (IC), use a hot-air system for any solder rework to modify the EVM for the purpose of repair or other application reasons.

#### 4.3.2 Equipment Connection

Use the following steps when connecting equipment:

1. Set the input power supplies to have a maximum voltage based on the recommended maximum in the data sheet, and turn the power supplies off.
2. Connect the positive voltage lead from the input power supply to VIN at the J6 connector of the EVM.
3. Connect the ground lead from the input power supply to GND at the J9 connector of the EVM.
4. Connect a load between OUT and GND. The connector used depends on the desired output current.
5. Disable the output by floating J8.

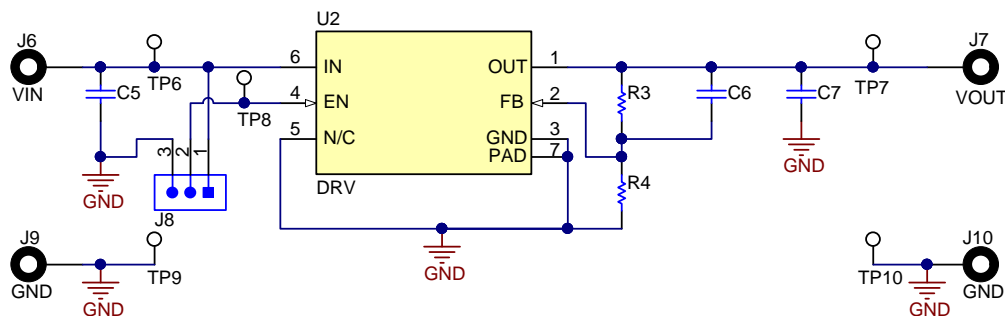
### 4.4 Operation

Operate the EVM with the following steps:

1. Turn on the power supplies.
2. Enable the output by jumping J8, the EN pin, to VIN.
3. Vary the respective load and input voltage as necessary for test purposes.

### 4.5 Schematic

Figure 2 is the schematic for the DRV portion of the EVM.



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NOTE: No components come populated on the board.

**Figure 3. MultiPkgLDOEVM-823 DRV Schematic**

## 5 DQN Package

### 5.1 Input/Output Connectors and Jumper Descriptions

#### 5.1.1 J11 – VIN

Input power-supply voltage connector. This is the jumper power-supply connection for the DQN package on the MultiPkgLDOEVM-823. Connect the load of the LDO to this pin.

#### 5.1.2 J12 – VOUT

Output power-supply voltage connector. This is the jumper power-supply connection for the DQN package on the MultiPkgLDOEVM-823. Connect the power supply to this jumper pin.

#### 5.1.3 J13 – GND

GND jumper. Connect the GND leads of the input power supply to this jumper.

#### 5.1.4 J14 – EN

Output enable. To enable the output, connect a jumper to short VIN to EN.

#### 5.1.5 J15 – GND

GND jumper. Connect the GND leads of the load to this jumper.

#### 5.1.6 TP11 – VIN

Input test point. Connect DMM or scope probes to this point to monitor the input voltage of the LDO.

#### 5.1.7 TP12 – VOUT

VOUT test point. Connect DMM or scope probes to this point to monitor the output of the LDO.

#### 5.1.8 TP13 – EN

This test point connects to EN. When J3 is removed, this testpoint can be used to drive the EN pin of the LDO.

#### 5.1.9 TP14 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

#### 5.1.10 TP15 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

### 5.2 Component Descriptions

#### 5.2.1 C8 - Input Capacitor

Populate the recommended input capacitor for the part that is being used.

#### 5.2.2 C9 - Output Capacitor

Populate the recommended output capacitor for the part that is being used.

### 5.3 EVM Setup

This section describes how to properly connect and setup the MultiPkgLDOEVM-823 for the DQN package, including the jumpers and connectors on the EVM board.

#### 5.3.1 Soldering Guidelines

To avoid damaging the integrated circuit (IC), use a hot-air system for any solder rework to modify the EVM for the purpose of repair or other application reasons.

#### 5.3.2 Equipment Connection

Use the following steps when connecting equipment:

1. Set the input power supplies to have a maximum voltage based on the recommended maximum in the data sheet, and turn the power supplies off.
2. Connect the positive voltage lead from the input power supply to VIN at the J11 connector of the EVM.
3. Connect the ground lead from the input power supply to GND at the J13 connector of the EVM.
4. Connect a load between OUT and GND. The connector used depends on the desired output current.
5. Disable the output by floating J14.

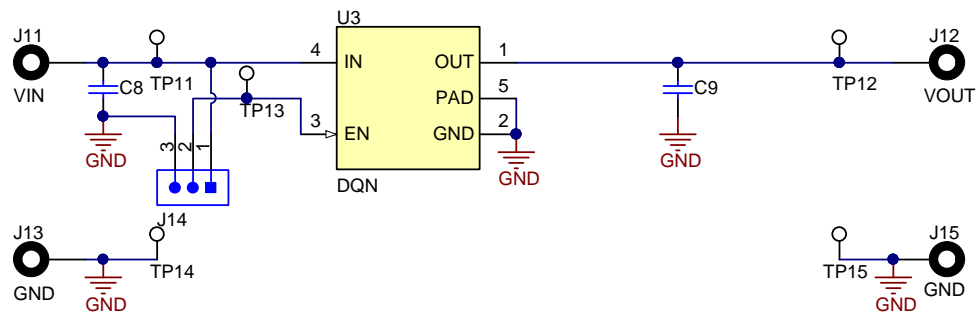
### 5.4 Operation

Operate the EVM with the following steps:

1. Turn on the power supplies.
2. Enable the output by jumping J14, the EN pin, to VIN.
3. Vary the respective load and input voltage as necessary for test purposes.

### 5.5 Schematic

Figure 2 is the schematic for the DQN portion of the EVM.



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NOTE: No components come populated on the board.

**Figure 4. MultiPkgLDOEVM-823 DQN Schematic**

## 6 DBV Package

### 6.1 Input/Output Connectors and Jumper Descriptions

#### 6.1.1 J16 – VIN

Input power-supply voltage connector. This is the jumper power-supply connection for the DBV package on the MultiPkgLDOEVM-823. Connect the load of the LDO to this pin.

#### 6.1.2 J17 – VOUT

Output power-supply voltage connector. This is the jumper power-supply connection for the DBV package on the MultiPkgLDOEVM-823. Connect the power supply to this jumper pin.

#### 6.1.3 J18 – EN

Output enable. To enable the output, connect a jumper to short VIN to EN.

#### 6.1.4 J19 – GND

GND jumper. Connect the GND leads of the input power supply to this jumper.

#### 6.1.5 J20 – GND

GND jumper. Connect the GND leads of the load to this jumper.

#### 6.1.6 TP16 – VIN

Input test point. Connect DMM or scope probes to this point to monitor the input voltage of the LDO.

#### 6.1.7 TP17 – VOUT

VOUT test point. Connect DMM or scope probes to this point to monitor the output of the LDO.

#### 6.1.8 TP18 – EN

This test point connects to EN. When J3 is removed, this testpoint can be used to drive the EN pin of the LDO.

#### 6.1.9 TP19 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

#### 6.1.10 TP20 – GND

GND test point. Connect GND lead of scope probes and power supply to this point.

### 6.2 Component Descriptions

#### 6.2.1 C10 - Input Capacitor

Populate the recommended input capacitor for the part that is being used.

#### 6.2.2 C11 - Feedforward Capacitor

Populate the recommended feedforward capacitor for the part that is being used. Feedforward capacitors can only be used on adjustable LDOs, consult the data sheet for the proper feedforward capacitor.

**6.2.3 C12 - Output Capacitor**

Populate the recommended output capacitor for the part that is being used.

**6.2.4 R5 - RTOP**

This is the top feed back resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R5. This resistor is only necessary for adjustable LDOs.

**6.2.5 R6 - RBOT**

This is the bottom feed back resistor. Populate with the resistance value that will give the desired output. See the data sheet for the equation to calculate R6. This resistor is only necessary for adjustable LDOs.

## 6.3 EVM Setup

This section describes how to properly connect and setup the MultiPkgLDOEVM-823 for the SOT-23 package, including the jumpers and connectors on the EVM board.

### 6.3.1 Soldering Guidelines

To avoid damaging the integrated circuit (IC), use a hot-air system for any solder rework to modify the EVM for the purpose of repair or other application reasons.

### 6.3.2 Equipment Connection

Use the following steps when connecting equipment:

1. Set the input power supplies to have a maximum voltage based on the recommended maximum in the data sheet, and turn the power supplies off.
2. Connect the positive voltage lead from the input power supply to VIN at the J16 connector of the EVM.
3. Connect the ground lead from the input power supply to GND at the J19 connector of the EVM.
4. Connect a load between OUT and GND. The connector used depends on the desired output current.
5. Disable the output by floating J18.

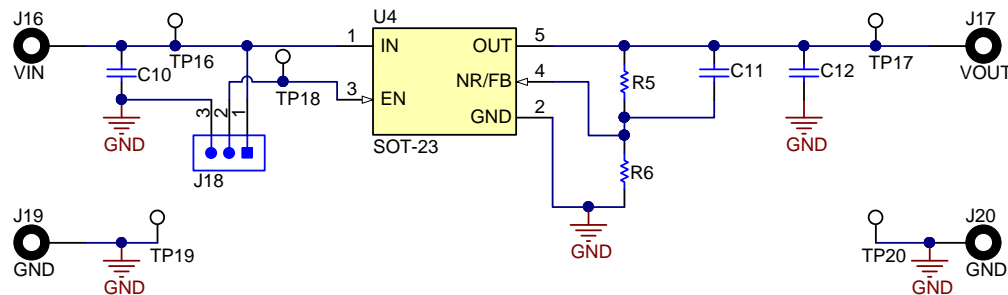
## 6.4 Operation

Operate the EVM with the following steps:

1. Turn on the power supplies.
2. Enable the output by jumping J18, the EN pin, to VIN.
3. Vary the respective load and input voltage as necessary for test purposes.

## 6.5 Schematic

Figure 5 is the schematic for the SOT-23 portion of the EVM.



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NOTE: No components come populated on the board.

**Figure 5. MultiPkgLDOEVM-823 DBV Schematic**

## 7 PCB Layout

Figure 6 to Figure 9 illustrate the PCB layout for this EVM.

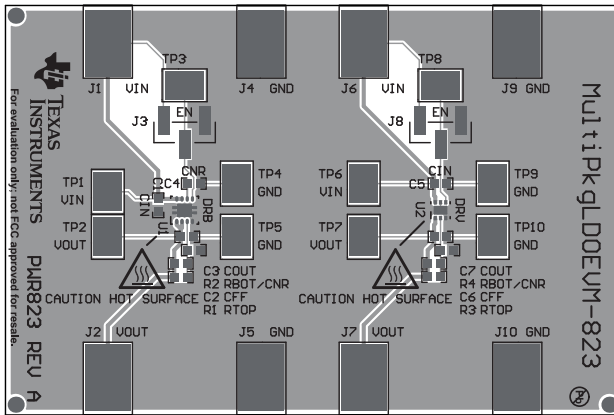


Figure 6. Top Layer Assembly

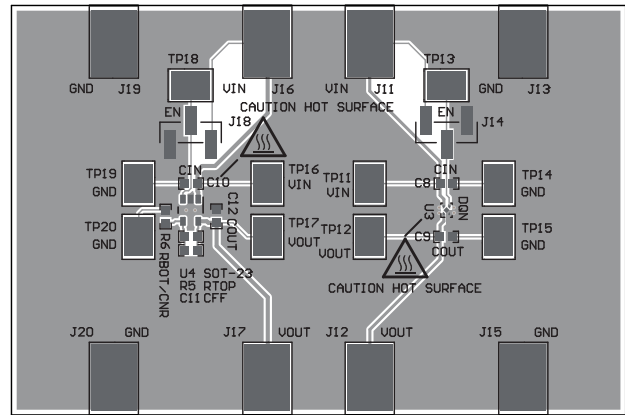


Figure 7. Bottom Layer Assembly

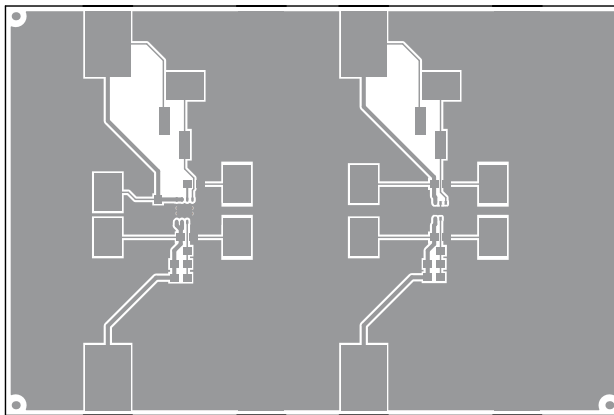


Figure 8. Top Layer Routing

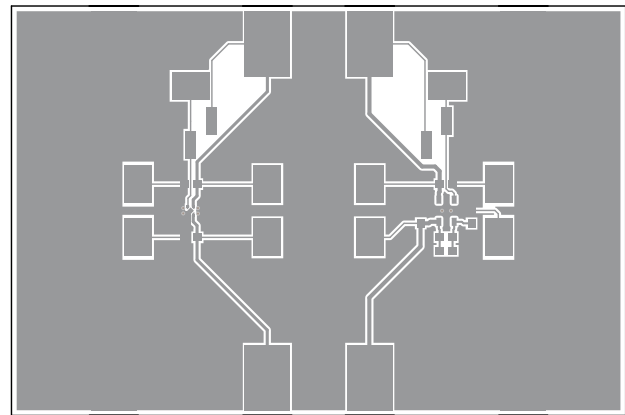


Figure 9. Bottom Layer Routing

## 8 Bill of Materials

Table 1 shows the BOM for this EVM.

**Table 1. MultiPkgLDOEVM-823 BOM<sup>(1)(2)(3)</sup>**

Designator	Quantity	Value	Description	Package Reference	PartNumber	Manufacturer
!PCB1	1		Printed Circuit Board		PWR823	Any
C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12	0	0.01uF	CAP, CERM, 0.01 μF, 50 V, + /- 10%, X7R, 0603	0603	GRM188R71 H103KA01D	MuRata
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A
J1, J2, J6, J7, J11, J12, J16, J17	0		Standard Banana Jack, Insulated, Red	6091	6091	Keystone
J3, J8, J14, J18	0		Header, 100 mil, 3x1, Gold, SMT	Samtec_TSM-103-01-X-SV	TSM-103-01-L-SV	Samtec
J4, J5, J9, J10, J13, J15, J19, J20	0		Standard Banana Jack, Insulated, Black	6092	6092	Keystone
R1, R2, R3, R4, R5, R6	0	0	RES, 0, 5%, 0.1 W, 0603	0603	CRCW06030000Z0EA	Vishay-Dale
TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20	0	SMT	Test Point, Compact, SMT	Testpoint_Keystone_Compact	5016	Keystone
U1	0		Most LDOs in the DRB package	DRB0008A	TPS7A8001DRBR <sup>(3)</sup>	Texas Instruments
U2	0		Most LDOs in the DRV package	DRV0006A	TPS7A3701DRVR <sup>(3)</sup>	Texas Instruments
U3	0		Most LDOs in the DQN package	DQN0004A	TLV73310PDQNR <sup>(3)</sup>	Texas Instruments
U4	0		Most LDOs in the SOT-23 package	DBV0005A	TPS73101DBVR <sup>(3)</sup>	Texas Instruments

<sup>(1)</sup> These assemblies are ESD sensitive, observe ESD precautions.

<sup>(2)</sup> These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

<sup>(3)</sup> This is an example part number. Any LDO in a supported pinout and package can be populated by the user.



## STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
  - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductor products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
  - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
  - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
  - 3.1 *United States*
    - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
    - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

### CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

### FCC Interference Statement for Class A EVM devices

*NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*

## **FCC Interference Statement for Class B EVM devices**

*NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:*

- *Reorient or relocate the receiving antenna.*
- *Increase the separation between the equipment and receiver.*
- *Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.*
- *Consult the dealer or an experienced radio/TV technician for help.*

### **3.2 Canada**

3.2.1 *For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247*

#### **Concerning EVMs Including Radio Transmitters:**

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### **Concernant les EVMs avec appareils radio:**

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### **Concerning EVMs Including Detachable Antennas:**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

#### **Concernant les EVMs avec antennes détachables**

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

### **3.3 Japan**

3.3.1 *Notice for EVMs delivered in Japan:* Please see [http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page) 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。  
[http://www.tij.co.jp/lstds/ti\\_ja/general/eStore/notice\\_01.page](http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page)

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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#### 3.4 *European Union*

##### 3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

#### 4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

##### 4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

6. *Disclaimers:*
- 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
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10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

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